

PCN#20141105000 Qualification of new BOM and Assembly Site for Select Device(s) Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (<u>PCN_ww_admin_team@list.ti.com</u>).

Sincerely,

PCN Team SC Business Services Phone: +1(214) 480-6037 Fax: +1(214) 480-6659

PCN# 20141105000 Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number: 20141105000					PCN Date	e:	12/03/2014				
Title: Qualification of new BOM and Assembly Site for Select Device(s)											
	Customer Contact:PCN ManagerPhone:+1(214)480-6037Dept:					Dept:	Q	uality Services			
Propose Date:							e provided at nple request				
Change [•]	Туре:										
Asse	embly Site		\boxtimes	Assemb	ly F	Process		\square	Assembly I	Mate	erials
Desi	gn			Electrica	I S	pecificat	ion		Mechanica	l Sp	ecification
Test	Site			Packing	/Sh	hipping/L	abeling		Test Process		
Waf	e <mark>r Bump Si</mark>	te		Wafer Bump Material				Wafer Bump Process			
Wafer Fab Site Wafer Fab Materials				S		Wafer Fab	Pro	cess			
	PCN Details										
Descript	ion of Cha	nge	:								

Texas Instruments is pleased to announce the qualification of new material set for the devices listed in Group 1 below and a new assembly site and material set for the devices listed in Group 2 listed below:

Group 1 will add Cu wire as a bond wire option. Devices will remain in current assembly facility. Group 2 will add a new assembly site and Cu wire as a bond wire option.

Group 1 Devices:

	Current	New
Bond Wire type	Au	Cu, Au

Group 2 Devices:

	Current	New
Assembly Site	SCSAT	TI Clark
Mount Compound	R008-0097X	4207123
Mold Compound	R003-0301X	4208625
Bond Wire Type	Au	Cu, Au
	Punch	Saw
Package Singulation	Pin 1 Index Area 1.00	PIN 1 NEEX AREA TOP AND BOTTOM

Note: The sawn package is considered backwards compatible with the punched package, i.e. no PCB footprint change is necessary. Packing materials (shipping boxes, tape & reels, etc.) at the additional site will be consistent with materials currently in use at the current site.

Reason for Change:

Continuity of supply.

- 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
- 2) Maximize flexibility within our Assembly/Test production sites.
- 3) Cu is easier to obtain and stock

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Changes to product identification resulting from this PCN:

Group 1 Devices: None

Group 2 Devices:

Assembly Site		
STATS ChipPAC A/T	Assembly Site Origin (22L)	ASO: STS
TI Clark	Assembly Site Origin (22L)	ASO: QAB

Sample product shippi	ng lab	el (not actual p	roduct label)
TEXAS INSTRUMENTS MADE IN: Malaysia	A G4		(1P) SN74LS07NSR

MADE IN: Malaysia (Q) 2000 (D) 0336 20C: 20: MSL 2 /260C/1 YEAR SEAL DT (31T) LOT: 3959047MLA MSL 1 /235C/UNLIM (3/29/04) OPT: 39 LBL: 5A (L)T0:1750 (2P) REV: ASSEMBLY SITE CODES: SCSAT = G, TI-Clark = 1							
	ected: Cu wire change						
CD4051BM96G3	LM224DRG3	NE555DRG3	SN74LV4052ADRG3				
CD4052BM96G3	LM239DRG3	RC4558DRG3	SN74LV595ADRG3				
CD4052BPWRG3	LM258DRG3	SN74ACT08DRG3	SN74LV595APWRG3				
CD4053BM96G3	LM2901DRG3	SN74AHC14DRG3	SN74LVC04ADRG3				
CD4053BPWRG3	LM2901PWRG3	SN74AHC14PWRG3	SN74LVC04APWRG3				
CD74HC4051M96G3	LM2902DRG3	SN74HC04DRG3	SN74LVC07ADRG3				
CD74HC4052M96G3	LM2902PWRG3	SN74HC138DRG3	SN74LVC07APWRG3				
CD74HC4053M96G3	LM2903DRG3	SN74HC14DRG3	SN74LVC08ADRG3				
CD74HC4053PWRG3	LM2903PWRG3	SN74HC164DRG3	SN74LVC08APWRG3				
CD74HC4094M96G3	LM2904DRG3	SN74HC165DRG3	SN74LVC125ADRG3				
CDCM6208V1HRGZR	LM2904PWRG3	SN74HC166DRG3	SN74LVC125APWRG3				
CDCM6208V1HRGZT	LM293DRG3	SN74HC595DRG3	SN74LVC14ADRG3				
CDCM6208V1RGZR	LM324DRG3	SN74HCT14DRG3	SN74LVC14APWRG3				
CDCM6208V1RGZT	LM324PWRG3	SN74LV07APWRG3	SN74LVC157ADRG3				
CDCM6208V1YRGZR	LM339DRG3	SN74LV08APWRG3	SN74LVC244APWRG3				
CDCM6208V1YRGZT	LM339PWRG3	SN74LV14APWRG3	SN74LVC245APWRG3				
CDCM6208V1ZRGZR	LM358DRG3	SN74LV165ADRG3	SN74LVC32APWRG3				
CDCM6208V1ZRGZT	LM358PWRG3	SN74LV165APWRG3	ULN2003ADRG3				

CDCM6208V2RGZR	LM393DRG3	SN74LV244APWRG3	ULN2004ADRG3	
CDCM6208V2RGZT	LM393PWRG3	SN74LV245APWRG3		
Group 2 Product Aff	ected: Assembly Site a	and Cu wire change		
CC1020RSS	CC1020RSST	CC1021RSSR	HPA00471RSSR	
CC1020RSSR	CC1021RSS			

G	Group 1 Devices - Qualification Data						
This qualification has been d		•	U				
validates that the proposed change meets the applicable released technical specifications.							
Qua	al V	ehicle 1: CDCM6	208V1RGZ (MSL3-2	60C)			
		Package Const	ruction Details				
Assembly Site:	TI (Clark AT	Mold Compou	ınd: 420	8625		
# Pins-Designator, Family:	48-	RGZ, VQFN	Mount Compou	ınd: 420	7768		
Lead frame (Finish, Base):	NiP	dAu, Cu	Bond W	/ire: 0.8	Mil Dia., Cu		
Qualification: 🗌 Plan	\square	Test Results					
Reliability Test		Conditions		S	ample Size/Fail		
ESD - HBM		3000V			3/0		
ESD - CDM		1500V			3/0		
Manufacturability		(per mfg. Site spe	ecification)		Pass		
Qu	al V	ehicle 2: CDCM62	208V2RGZ (MSL3-2	60C)			
		Package Const	ruction Details				
Assembly Site:	TI (Clark AT	Mold Compou	ind: 420	8625		
# Pins-Designator, Family:	48-	RGZ, VQFN	Mount Compound: 4		7768		
Lead frame (Finish, Base):	NiP	dAu, Cu) Mil Dia., Cu		
Qualification: 🗌 Plan	\square	Test Results					
Reliability Test		Conditions		S	ample Size/Fail		
**Autoclave		121C (96 hrs)			77/0		
**High Temp. Storage Bake		170C (420hrs)			77/0		
**Life Test		105C (1000hrs)			77/0		
**Temperature Cycle		-65C/+150C (500	Сус)		77/0		
ESD - HBM		1000V			3/0		
ESD - MM		100V			3/0		
ESD - CDM		500V			3/0		
Manufacturability		(per mfg. Site spe			Pass		
Notes **- Preconditioning	-						
C	lual	Vehicle 3: CD40	53BM96 (MSL1-260)C)			
	-	Package Const	ruction Details				
Assembly Site:	AS	ESH	Mold C	Compound	EN2000506		
# Pins-Designator, Family: 16-D, SOIC			Mount C	Compound	EY1000063		
Lead frame (Finish, Base):	Ма	tte Tin, Cu	E	Bond Wire:	1.0 Mil Dia., Cu		
Qualification: 🗌 Plan	\boxtimes	Test Results					
Reliability Test		Conditions		Sample Size/Fail			
**Life Test		150C (300 Hrs)			77/0		
Electrical Characterization							

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150C (1000 Hrs)			77 (0				
		77/0					
130C/85%RH (96	·		77/0				
130C/85%RH/33.			77/0				
-65C/+150C (500			77/0				
76 ball bonds, mir			76/0				
(per mfg. Site spe			Pass				
		<u> </u>					
	•	;)					
		•	EN2000506				
		•	EY1000063				
	E	Bond Wire:	1.0 Mil Dia., Cu				
<u> </u>							
Conditions		Sar	nple Size/Fail				
150C (300 Hrs)			77/0				
-			Pass				
150C (1000 Hrs)			77/0				
130C/85%RH (96	Hrs)		77/0				
130C/85%RH/33.	3 psia (96 Hrs)	77/0					
	-65C/+150C (500 Cyc)		77/0				
		76/0					
nce: (Level 1-260C +5/-0	0C)						
ual Vehicle 5: RC45	58DR (MSL1-2600	C)					
			Γ				
ASESH		•	EN2000506				
B-D, SOIC	Mount C	ompound:	EY1000063				
	E	Bond Wire:	1.0 Mil Dia., Cu				
Conditions		Sar	nple Size/Fail				
150C (300 Hrs)			77/0				
-			Pass				
	150C (1000 Hrs)		77/0				
	130C/85%RH (96 Hrs)		77/0				
	130C/85%RH/33.3 psia (96 Hrs)		77/0				
-65C/+150C (500			77/0				
76 ball bonds, mir							
Manufacturability (per mfg. Site sp			Pass				
	Notes: ** Preconditioning sequence: (Level 1-260C +5/-0C)						
nce: (Level 1-260C +5/-0	,		1 435				
	,	C)	1 435				
ual Vehicle 6: LMV3 Package Consti	58IDR (MSL1-2600 ruction Details						
nce: (Level 1-260C +5/-0 ual Vehicle 6: LMV3 Package Consti ASESH	58IDR (MSL1-2600 ruction Details Mold C	ompound:	EN2000506				
nce: (Level 1-260C +5/-0 ual Vehicle 6: LMV3 Package Consti ASESH 3-D, SOIC	558IDR (MSL1-2600 ruction Details Mold C Mount C	ompound: ompound:	EN2000506 EY1000063				
nce: (Level 1-260C +5/-0 ual Vehicle 6: LMV3 Package Consti ASESH B-D, SOIC Matte Tin, Cu	558IDR (MSL1-2600 ruction Details Mold C Mount C	ompound:	EN2000506				
nce: (Level 1-260C +5/-0 ual Vehicle 6: LMV3 Package Consti ASESH 3-D, SOIC	558IDR (MSL1-2600 ruction Details Mold C Mount C	ompound: ompound:	EN2000506 EY1000063				
nce: (Level 1-260C +5/-0 ual Vehicle 6: LMV3 Package Consti ASESH B-D, SOIC Matte Tin, Cu	558IDR (MSL1-2600 ruction Details Mold C Mount C	ompound: ompound: Bond Wire:	EN2000506 EY1000063				
	ASESH B-D, SOIC Watte Tin, Cu XESSH B-D, SOIC Watte Tin, Cu Test Results Conditions 150C (300 Hrs) - 150C (1000 Hrs) 130C/85%RH (96 130C/85%RH/33. -65C/+150C (500 76 ball bonds, min (per mfg. Site specence: (Level 1-260C +5/-4) Vehicle 5: RC45 Package Constr ASESH 3-D, SOIC Vatte Tin, Cu Test Results Conditions 150C (300 Hrs) - 150C (300 Hrs) - 150C (1000 Hrs) 150C (300 Hrs) - 150C (1000 Hrs) 130C/85%RH (96 130C/85%RH (96	nce: (Level 1-260C +5/-0C) Package Construction Details ASESH Mold C 3-D, SOIC Mount C Matte Tin, Cu E Test Results Conditions 150C (300 Hrs) - 150C (1000 Hrs) 130C/85%RH (96 Hrs) 130C/85%RH (96 Hrs) 130C/85%RH (96 Hrs) -65C/+150C (500 Cyc) 76 ball bonds, min. 3 units (per mfg. Site specification) nce: (Level 1-260C +5/-0C) ual Vehicle 5: RC4558DR (MSL1-260C Package Construction Details ASESH Mold C 3-D, SOIC Mount C Mold C Seconstruction Details ASESH Mold C 3-D, SOIC Mount C Matte Tin, Cu E Seconstruction Details ASESH ASESH Mold C 3-D, SOIC Mount C Matte Tin, Cu E Test Results Conditions 150C (300 Hrs) - - 150C (1000 Hrs) 130C/85%RH (96 Hrs) 130C/85%RH (96 Hrs) 130C/85%RH/33.3 psia (96 Hrs)	nce: (Level 1-260C +5/-0C) Package Construction Details ASESH Mold Compound: B-D, SOIC Mount Compound: Matte Tin, Cu Bond Wire: Conditions Sar 150C (300 Hrs) - 150C (1000 Hrs) 130C/85%RH (96 Hrs) 130C/85%RH/33.3 psia (96 Hrs) -65C/+150C (500 Cyc) 76 ball bonds, min. 3 units (per mfg. Site specification) nce: (Level 1-260C +5/-0C) Package Construction Details ASESH Mold Compound: BASESH MOLD CO				

**Life Test	150C (300 Hrs)		77/0	77/0		
**High Temp. Storage Bake	· · /		77/0			
**Biased HAST	130C/85%RH (19	2 Hrs)	80/0	80/0		
**Unbiased HAST		130C/85%RH/33.3 psia (96 Hrs)		-		
**T/C -65C/150C	-65C/+150C (500		77/0 77/0			
Bond Strength	76 ball bonds, mir		80/0			
Manufacturability	(per mfg. Site spe		Pass			
Notes: ** Preconditioning sequ			F 835			
	al Vehicle 7: SN74H		50C)			
	Package Constr	•				
Assembly Site:	ASESH	Mold C	Compound:	EN2000506		
# Pins-Designator, Family:	16-D, SOIC		Compound:	EY1000063		
Lead frame (Finish, Base):	Matte Tin, Cu		Sond Wire:	0.8 Mil Dia., Cu		
Qualification: Plan	Test Results	·				
			Sar	nple Size/Fail		
Reliability Test	Conditions		Lot# 1	Lot# 2		
**Life Test	150C (300 Hrs)		77/0	77/0		
**High Temp. Storage Bake			77/0	77/0		
**Biased HAST	130C/85%RH (19	2 Hrs)	80/0	80/0		
**Unbiased HAST	130C/85%RH/33.	/	77/0	77/0		
**T/C -65C/150C	-65C/+150C (500		77/0	77/0		
Bond Strength	76 ball bonds, mir		80/0	80/0		
Manufacturability	(per mfg. Site spe		Pass	Pass		
Notes: ** Preconditioning sequ			1 400	1 400		
	al Vehicle 8: SN74L		50C)			
	Package Constr	ruction Details				
Assembly Site:	ASESH	Mold C	Compound:	EN2000506		
# Pins-Designator, Family:	14-D, SOIC	Mount C	Compound:	EY1000063		
Lead frame (Finish, Base):	Matte Tin, Cu		Bond Wire:	0.8 Mil Dia., Cu		
Qualification: Plan	Test Results			<u>I</u>		
Reliability Test	Conditions		Sar	nple Size/Fail		
**Life Test	150C (300 Hrs)		77/0			
Electrical Characterization	-		Pass			
**High Temp. Storage Bake	170C (600 Hrs)	170C (600 Hrs)		77/0		
**Biased HAST		130C/85%RH (192 Hrs)		77/0		
**Unbiased HAST		130C/85%RH/33.3 psia (192 Hrs)		77/0		
**T/C -65C/150C		-65C/+150C (500 Cyc)		77/0		
Bond Strength	76 ball bonds, mir					
Manufacturability	(per mfg. Site spe			Pass		
Notes: ** Preconditioning sequ						
Qu	al Vehicle 9: SN74L	/14ADR (MSL1-26	50C)			
	Package Constr					
Assembly Site:	ASESH		Compound:	EN2000506		
# Pins-Designator, Family:	14-D, SOIC	Mount C	Compound:	EY1000063		
Lead frame (Finish, Base):	Matte Tin, Cu		Bond Wire:	1.0 Mil Dia., Cu		
Qualification: 🗌 Plan	Test Results					
Reliability Test	Conditions		Sar	mple Size/Fail		

**Life Test	150C (300 Hrs)			77/0
Electrical Characterization	-		Pass	
**High Temp. Storage Bake	150C (1000 Hrs)		77/0	
**Biased HAST	130C/85%RH (96	Hrs)	77/0	
**Unbiased HAST	130C/85%RH/33			77/0
**T/C -65C/150C	-65C/+150C (500			77/0
Bond Strength	76 ball bonds, mi			76/0
Manufacturability	(per mfg. Site spe	ecification)		Pass
Notes: ** Preconditioning seque	ence: (Level 1-260C +5/-	0C)		
Q	ual Vehicle 10: RC4	558PWR (MSL1-260)C)	
	Package Const	ruction Details		
Assembly Site:	ASESH	Mold C	ompound:	EN2000508
# Pins-Designator, Family:	8-PW, TSSOP	Mount C	ompound:	EY1000063
Lead frame (Finish, Base):	Matte Tin, Cu	E	Bond Wire:	1.0 Mil Dia., Cu
Qualification: 🗌 Plan	Test Results			
Reliability Test	Conditions		Sar	nple Size/Fail
Electrical Characterization	-			Pass
**Life Test	150C (300 Hrs)			77/0
**High Temp. Storage Bake	150C (1000 Hrs)			77/0
**Biased HAST	130C/85%RH (96	o Hrs)	77/0	
**Unbiased HAST	130C/85%RH/33	3 psia (96 Hrs)	77/0	
**T/C -65C/150C	-65C/+150C (500) Сус)		77/0
Bond Strength	76 ball bonds, mi			76/0
Manufacturability	(per mfg. Site spe			Pass
Notes: ** Preconditioning seque			(
Qua	al Vehicle 11: SN74L	· · · · · · · · · · · · · · · · · · ·	60C)	
	Package Const			510000500
Assembly Site:	ASESH		ompound: ompound:	EN2000508
# Pins-Designator, Family:	14-PW, TSSOP			EY1000063
Lead frame (Finish, Base): Qualification: Plan	Matte Tin, Cu	E	Bond Wire:	1.0 Mil Dia., Cu
			Corr	
Reliability Test	Conditions		Sar	nple Size/Fail
Electrical Characterization	-			Pass
**Life Test	150C (300 Hrs)		77/0	
**High Temp. Storage Bake			77/0	
**Biased HAST	130C/85%RH (96		77/0	
**Unbiased HAST	130C/85%RH/33		77/0	
**T/C -65C/150C	-65C/+150C (500			77/0
Bond Strength	76 ball bonds, mi			76/0
Manufacturability Notes: ** Preconditioning seque	(per mfg. Site spece: (Level 1-260C +5/-			Pass
	ual Vehicle 12: ULN2	•	00)	
	Package Const			
Assembly Site:	ASESH		ompound:	EN2000508
# Pins-Designator, Family:	16-PW, TSSOP		ompound:	EY1000063
Lead frame (Finish, Base):	Matte Tin, Cu		Bond Wire:	1.0 Mil Dia., Cu
Qualification: Plan	X Test Results			

Reliability Test	Conditions		Sample Size/Fail		
Electrical Characterization	-		Pass		
**Life Test	150C (300 Hrs)			77/0	
**High Temp. Storage Bake	150C (1000 Hrs)			77/0	
**Biased HAST	130C/85%RH (96	Hrs)		77/0	
**Unbiased HAST	130C/85%RH/33.	3 psia (96 Hrs)		77/0	
**T/C -65C/150C	-65C/+150C (500) Cyc)		77/0	
Bond Strength	76 ball bonds, mi	n. 3 units		76/0	
Manufacturability	(per mfg. Site spe	· · · · ·		Pass	
Notes: ** Preconditioning seque	ence: (Level 1-260C +5/-	0C)			
Qu	al Vehicle 13: TPL74	107LPWR (MSL1-26	oc)		
	Package Const	ruction Details			
Assembly Site:	ASESH	ESH Mold C		EN2000508	
# Pins-Designator, Family:	16-PW, TSSOP	Mount C	ompound:	EY1000063	
Lead frame (Finish, Base):	Matte Tin, Cu	Bond Wire:		1.0 Mil Dia., Cu	
Qualification: 🗌 Plan	Test Results				
Reliability Test	Conditions	Conditions		nple Size/Fail	
**Biased HAST	130C/85%RH (96	130C/85%RH (96 Hrs)		77/0	
**Unbiased HAST	130C/85%RH/33.	3 psia (96 Hrs)	77/0		
**Autoclave	121C (96 Hrs)			77/0	
**T/C -65C/150C	-65C/+150C (50C) Cyc)	77/0		
**High Temp. Storage Bake				77/0	
Notes: ** Preconditioning sequ	ence: (Level 1-260C +5/-	0C)			

Group 2 Devices - Qualification Data								
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.								
Qual Vehicle # 1: CC1020 (MSL3-260C)								
Package Construction Details								
Assembly Site:	TI Clark AT	Mold Compour	ind: 420		208625			
# Pins-Designator, Family:	32-RSS, VQFN	Mount Compour	nd:	4207123				
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire: 1.0 M		1.0 M	.0 Mil Dia., Cu			
Qualification: 🗌 Plan 🛛 Test Results								
Reliability Test	Conditions		Sample Size/Fail			Fail		
		Conditions		ot#1	Lot#2	Lot#3		
**High Temp. Storage Bake	150C (600hrs)	150C (600hrs)		7/0	77/0	77/0		
**Unbiased HAST	110C/85%RH (26	110C/85%RH (264hrs)		7/0	77/0	77/0		
**Biased Temp Humidity	85C/85%RH (634	85C/85%RH (634 Hrs)		6/0	26/0	26/0		
* * Temperature Cycle	-55C/+125C (500	-55C/+125C (500 Cyc)		7/0	77/0	77/0		
ESD - CDM	250V/250V		1	/0	1/0	1/0		
ESD - CDM	SD - CDM 500V/500V		1/0		1/0	1/0		
ESD - CDM	- CDM 750V/750V		1/0		1/0	1/0		
Manufacturability (per mfg. Site specification)		ecification)	Pass		Pass	Pass		
Notes **- Preconditioning sequence: Level 3-260C.								
Qual Vehicle # 2: CC1150 (MSL3-260C)								
Package Construction Details								
Assembly Site:	TI Clark AT	ark AT Mold Compound: 4208625						

# Pins-Designator, Family: 16	-RGV, VQFN	Mount Compoun	Compound: 4207123					
Lead frame (Finish, Base): Ni	PdAu, Cu	Bond Wir	e: 0.8	0.80 Mil Dia., Cu				
Qualification: Plan Test Results								
Deliebility Teet	Conditions		Sample Size/Fail					
Reliability Test			Lot#1	Lot#2	Lot#3			
**High Temp. Storage Bake	150C (600hrs)	77/0	77/0	77/0				
**Unbiased HAST	110C/85%RH (264hrs)		78/0	78/0	78/0			
**Temperature Cycle	erature Cycle -55C/+125C (500 Cyc)		78/0	78/0	78/0			
ESD - CDM	250V/250V		1/0	1/0	1/0			
ESD - CDM	500V/500V		1/0	1/0	1/0			
Manufacturability	(per mfg. Site specification)			Pass	Pass			
Notes **- Preconditioning sequence: Level 3-260C.								
Supporting QBS : CC1101 (MSL3-260C)								
Package Construction Details								
Assembly Site:	TI Clark AT	Mold Compound: 4208625						
# Pins-Designator, Family:	20-RGP, VQFN	Mount Compound:	4207123					
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.8 Mil Dia., Cu					
Qualification: Plan Test Results								
Deliability Test	Conditions		Sample Size/Fail					
Reliability Test			Lot#1	Lot#2	Lot#3			
**High Temp. Storage Bake	150C (600hrs)		77/0	77/0	77/0			
**Biased Temp Humidity	85C/85%RH (600 Hrs)		25/0	25/0	27/0			
**Unbiased HAST	110C/85%RH (264hrs)		77/0	77/0	77/0			
**Temperature Cycle	-55C/+125C (500 Cyc)		77/0	77/0	77/0			
ESD - HBM	1500V/1500V		3/0	3/0	3/0			
ESD - CDM	250V/250V		3/0	3/0	3/0			
ESD - CDM	500V/500V		3/0	3/0	3/0			
Manufacturability	(per mfg. Site specification)		Pass	-	-			
Notes **- Preconditioning sequence: Level 3-260C.								

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com